

## » Carrier Grade Server TIGH2U «



- » NEBS-3 / ETSI compliant
- » Long life support (3 years)
- » Short depth, ruggedized 2U chassis
- » Dual, redundant AC or DC power option
- » Telco alarm management
- » Hardware RAID option
- » Industry-leading performance/watt

Carrier Grade Server TIGH2U is a NEBS-3 and ETSI-compliant 2U carriergrade rack-mount server, delivering industry-leading performance-per-watt over previous-generation rackmount servers. It features the Quad-Core Intel® Xeon® processor 5400 series — based on Intel's latest 45nm technology — to provide breakthrough performance and energy efficiency for compute- and I/O-intensive applications and workloads.

This high-performing server is an excellent choice for the demanding environment and limited space of the central office and high availability

data centers. It enables OEMs and TEMs to create specialized, valueadded solutions for a variety of telecom applications including unified messaging, SoIP, call control, media and signaling gateways, and operational system support.

The TIGH2U is designed to be fire-resistant and to withstand extreme heat, humidity, altitude and zone 4 earthquake shock. Advanced server management and telco alarm management features provide visual, audible (optional) and SNMP event indications of faults, consistent with the rigid requirements of the telecom central office environment.

## Features & Benefits

### Standard Feature

Support for two Quad-Core Intel® Xeon® processors 5400 series

Three-year extended life cycle support with possible extension to five years

Shallow 20-inch depth

600W AC or DC hot-swap power supply

Telco alarm management

Two rear-panel GbE NIC (Cu) ports

Eight FB-DIMM slots (240-pin DDR2-533/667 MHz)

Drive trays for up to six hot-swap 2.5" SAS hard disk drives

Bay supports optical drive (purchased separately)

Up to five PCI slots for flexibility and additional I/O

### Optional Features

Hardware RAID 5

Intel® Remote Management Module 2

Flash storage capability supports 3rd party solid state drives (purchased separately)

Optional I/O modules (rear)

Additional full-height riser options for PCI-X

### Benefit

New 45nm enhanced Intel® Core™ microarchitecture boosts performance on multiple applications/user environments and data-demanding workloads

Faster performance with improved energy efficiency enables denser deployments

Reduces customer risk for long product roll-outs

Fewer platform transitions requiring additional testing and software

Increases installation and service flexibility

Flexibility of installation and applications; uninterrupted operation (DC)

Upgradeable to second power supply for redundancy

Front-panel feature supports central office alarm systems

Scalable Ethernet ports, upgradeable to 20 GbE (max) based on PCI configuration and optional I/O modules

Maximum 32 GB memory (non-mirrored mode)

High-performance, enterprise-class drives for 24/7 operation

Accommodates Slimline CD-ROM; CD-R/W; CD DVD-R/W

Low-profile riser supports two PCIe x4 slots

Full-height, full-length riser supports three slots (two PCIe x4 [or 1 PCIe x8] and one PCI-X)

### Benefit

Greater protection and reliability of data storage

Lights-out management

High-speed, high-density storage, faster boot times, USB interface

Enables additional external SAS storage or two additional GbE NIC (Cu) ports on rear panel

PCI-X (active): three independent PCI-X, each with maximum 133 MHz

PCI-X (passive): two PCI-X with maximum 100 MHz and one PCI-X (66 MHz) all on a shared PCI bus

## Technical Information

### Processor

Type

Two (2) Quad-Core Intel® Xeon® processors 5400 series with 12 MB cache

Front-side bus

1333 MHz

### Chipset

Memory controller hub

Intel® 5000P Memory Controller Hub (MCH)

I/O controller hub

Intel® 6321ESB I/O Controller Hub (ICH)

### Connections

Two (2) PCI risers supporting up to five PCI slots (included)

One (1) low-profile riser supporting two PCIe x4 slots

One (1) full-height, full-length riser supporting three slots (two PCIe x4 [or one PCIe x8] and one PCI-X)

Additional full-height riser configuration (optional)

PCI-X (active): Three (3) independent PCI-X slots (133 MHz max)

PCI-X (passive): Two (2) PCI-X slots (100 MHz max) and one PCI-X slot (66 MHz) on shared bus

GbE NIC (CU) ports

Two (2) on base board (rear)

Two (2) via optional I/O Module (rear, optional)

USB 2.0 ports

Three (3): One front/two rear

### Environmental

Temperature, operating

+5°C to +40°C (41° F to 104° F)

Temperature, short-term operating

(<96 hrs) -5°C to 50°C

Temperature, nonoperating

-40°C to 70°C (-40° F to 158° F)

Altitude

0 to 1,800 m (0 to 5,905 ft) @ 40°C

0 to 4,000 m (0 to 13,123 ft) @ 30°C

Humidity, operating

5% to 85%

Humidity, short-term operating

5% to 90%

Humidity, non-operating

93%, non-condensing at temperatures of 23° C (73° F) to 40° C (104° F)

Vibration, operating

Swept sine survey at an acceleration amplitude of 0.1 G from 5 to 100 Hz and back to 5 Hz at a rate of 0.1 octave/minute; 90 minutes per axis on all three axes as per Bellcore GR-63-CORE standards)

Vibration, non-operating

Swept sine survey at an acceleration amplitude of 0.5 G from 5 to 50 Hz at a rate of 0.1 octaves/minute, and an acceleration amplitude of 3.0 G from 50 to 500 Hz at a rate of 0.25 octaves/minute, on all three axes as per Bellcore GR-63-CORE standard. 2.2 Grms, 10 minutes per axis on all three axes

Half-sine 2 G, 11 ms pulse, 100 pulses in each direction, on each of the three axes

### Storage

Type

SAS 2.5" hot-swap HDD

Redundancy

RAID 1 and RAID 5

Internal

Carrier with six HDD trays

External

SAS port on rear supports JBOD

### Memory

Maximum memory capacity

32 GB (non-mirrored mode)

Number of DIMM slots

Eight (8)

Memory type

FB-DIMM technology at 533 and 667 MHz

### Physical

Height

3.45 inches (87.6 mm)

Width

17.14 inches (435.3 mm)

Depth

20 inches (508 mm)

### Regulatory Compliance

Safety

UL 60950-1, 1st Edition/CSA 22.2 60950-1, Low Voltage Directive 2006/95/EC, GS to EN60950-1, 1st Edition CB Certificate and Report to IEC60950-1, 1st Edition and all international deviations

Electromagnetic Compatibility:

Australia/New Zealand

C-tick, Class A

Canada

ICES-003, Issue 4, Class A Limit

Europe

EMC Directive, 2004/108/EC; EN55022, Class A Limit, Radiated and Conducted Emissions, EN55024 Immunity Characteristics for ITE; EN61000-4-2 ESD Immunity; EN61000-4-3 Radiated Immunity; EN61000-4-4 Electrical Fast Transient; EN61000-4-5 Surge; EN61000-4-6 Conducted RF; EN61000-4-8 Power Frequency Magnetic Fields; EN61000-4-11 Voltage Fluctuations and Short Interrupts; EN61000-3-2 Harmonic Currents; EN61000-3-3 Voltage Flicker

International

CISPR 22, Class A Limit, CISPR 24 Immunity

Japan

VCCI Class A

Korea

RRL Approval, Class A

Russia

Gost Approval

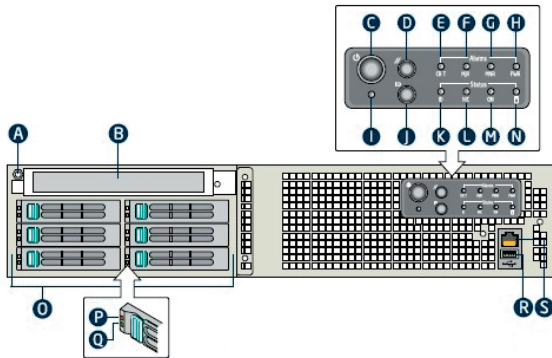
Taiwan

BSMI Approval, CNS 13438, Class A and CNS13436 Safety

USA

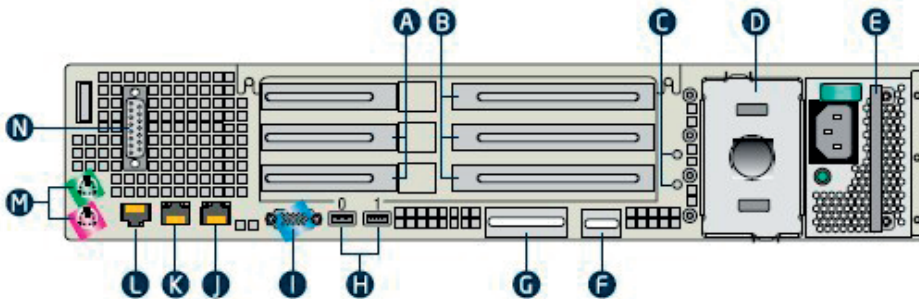
FCC 47 CFR Parts 2 and 15, Verified Class A Limit

## Carrier Grade Server Tigh2U front panel



- |   |                     |  |                              |
|---|---------------------|--|------------------------------|
| A – Anti-static connection                          | F – Major alarm LED | L – NIC activity LED                           | P – Drive fault indicator    |
| B – Optical drive bay<br>(optional) or filler panel | G – Minor alarm LED | M – Main power LED                             | (one per hard drive)         |
| C – Power switch                                    | H – Power alarm LED | N – HDD activity LED                           | Q – Drive activity indicator |
| D – Reset Switch                                    | I – NMI switch      | O – Hard drive bays<br>(supports six 2.5" SAS) | (one per hard drive)         |
| E – Critical alarm LED                              | J – ID switch       | R – USB port 2 connector                       |                              |
|   | K – System ID LED   | S – RJ45 serial port connector (COM 2)         |                              |

## Carrier Grade Server TIGH2U rear panel



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|--|--|
| A – Low-profile PCIe add-in cards or filler panels               | H – USB 0 and USB 1 port connectors    |
| B – Full-height PCI-X/PCIe add-in cards or filler panels         | I – Video connector                    |
| C – Grounding studs (for DC system)                              | J – GbE NIC 2 connector                |
| D – Power supply #2 slot (filler panel shown)                    | K – GbE NIC 1 connector                |
| E – Power supply #1 (AC module shown; DC modules also available) | L – RJ45 serial port connector (COM 2) |
| F – GCM port connector (optional) or filler panel                | M – PS/2 keyboard and mouse connectors |
| G – I/O expansion module connector (optional) or filler panel    | N – Telco alarms connector             |

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